

**NOTE:**

- MATERIAL:**  
CONTACTS—COPPER ALLOY.  
HOUSING—UL 94V-0 RATED LCP, COLOR:BLACK  
GROUNDING PLATE—COPPER ALLOY.  
ADHESIVE 3M#9460 HIGH TEMP DOUBLE SIDE, 0.05mm THICKNESS.
- FINISH:**  
Ⓧ CONTACTS—15u" MIN GOLD ON MATING AREA OR 5u" MIN. GOLD FLASH ON MATING AREA OVER Pd/Ni 10u" MIN. PLATING AT MATING AREA, 200u" TIN/LEAD OR 120u" TIN PLATING AT SOLDERING TAILS, OVER 50u" MIN. NICKEL UNDERPLATING OVERALL.  
GROUNDING PLATE—5u" MIN GOLD FLASH ON CONTACT AREA, OVER 10u" MIN. Pd/Ni PLATING AT CONTACT AREA, 100u" TIN/LEAD OR TIN PLATING AT SOLDERING TAILS, OVER 50u" MIN. NICKEL UNDERPLATING OVERALL.
- PROD. NUMBER: SEE 903-007-0000.**  
PROD.CODE SPECIFICATION.

9 03 - 0 07 - \*2 06 □

CUSTOMER SERIES TYPE: 903-007-0000  
CONTACT TYPE & MATING PORT: 07  
POSITION & CONNECTOR STYLE & TERMINATION TYPE: \*2  
MODIFICATION (FLOATING NO.): 06  
CONTACT FINISH: 06 = 15u" GOLD  
FOR SPECIAL REQUEST ONLY: □ = FOR GENERAL, R = FOR TAPE&REEL, Ⓧ = FOR LEAD FREE PLATING

4. RECOMMENDED PC BOARD THICKNESS: 0.56mmMAX.

REV	ECN NO	DESCRIPTION	APPD.	DATE
J	E17-2003-001	ADD P/N 903-007-0000 FOR LEAD FREE PLATING	Mari	04.22'2004
I	E17-2003-006	3 TIPS CHANGE 4 TIPS. DIM. G, DIM. HES—0.415	Mari	06.12'2003
H	E17-2003-034	1. CHANGE [0.018] ON TYPE III 2. ADD RY FOR DIMENSION. 3. CHANGE [0.018] ON TYPE I/II	Mari	04.09'2003
G	E17-2003-025	CANCEL TYPE III HOUSING'S CHAMFER	Mari	03.19'2003
F	E17-2002-100	ADD TYPE III WITHOUT ADHESIVE TAPE + 3 TIPS	Mari	12.18'2002
E	E17-2002-082	ADD DATE CODE "Z" BY CUSTOMER SPECIAL CODE PER CONTACT	Mari	11.29'2002
D	E17-2002-040	Modify pin dimensions to TYPE I/II	Terry	06.26'2002
C	E17-2001-036	BS-DIM.A, DIM. B, DIM. C, DIM. D, DIM. E, DIM. F, DIM. G, DIM. H, DIM. I, DIM. J, DIM. K, DIM. L, DIM. M, DIM. N, DIM. O, DIM. P, DIM. Q, DIM. R, DIM. S, DIM. T, DIM. U, DIM. V, DIM. W, DIM. X, DIM. Y, DIM. Z	Terry	06.21'2001
B	E17-2001-033	BS-DIM.A, DIM. B, DIM. C, DIM. D, DIM. E, DIM. F, DIM. G, DIM. H, DIM. I, DIM. J, DIM. K, DIM. L, DIM. M, DIM. N, DIM. O, DIM. P, DIM. Q, DIM. R, DIM. S, DIM. T, DIM. U, DIM. V, DIM. W, DIM. X, DIM. Y, DIM. Z	Terry	06.11'2001
A	E17-2001-020	DWG. REL.	Terry	04.17'2001

PROD. NO.	TYPE	DIM. A ±0.05	DIM. B ±0.05	DIM. C ±0.05	DIM. D	DIM. E	PROD. NO.	TYPE	DIM. A ±0.05	DIM. B ±0.05	DIM. C ±0.05	DIM. D	DIM. E
903-007-2106	WITHOUT ADHESIVE TAPE + 4 TIPS	+0.6mm	0.50	∅0.80	39.90	39.10	903-007-2306	WITHOUT ADHESIVE TAPE + 4 TIPS	+0.6mm	0.50	∅1.15	39.80	-
903-007-1106	WITH ADHESIVE TAPE	+0.3mm	0.50	∅0.80	39.90	39.10	903-007-1306	WITH ADHESIVE TAPE + 4 TIPS	+0.3mm	0.50	∅1.15	39.80	38.60
903-007-2006	WITH ADHESIVE TAPE	+0.6mm	0.50	∅1.15	39.90	39.10	903-007-2206	WITH ADHESIVE TAPE + 3 TIPS	+0.6mm	0.50	∅1.15	39.80	38.60
903-007-1006	WITH ADHESIVE TAPE	+0.3mm	0.50	∅1.15	39.90	39.10	903-007-1206	WITH ADHESIVE TAPE + 3 TIPS	+0.3mm	0.50	∅1.15	39.80	38.60

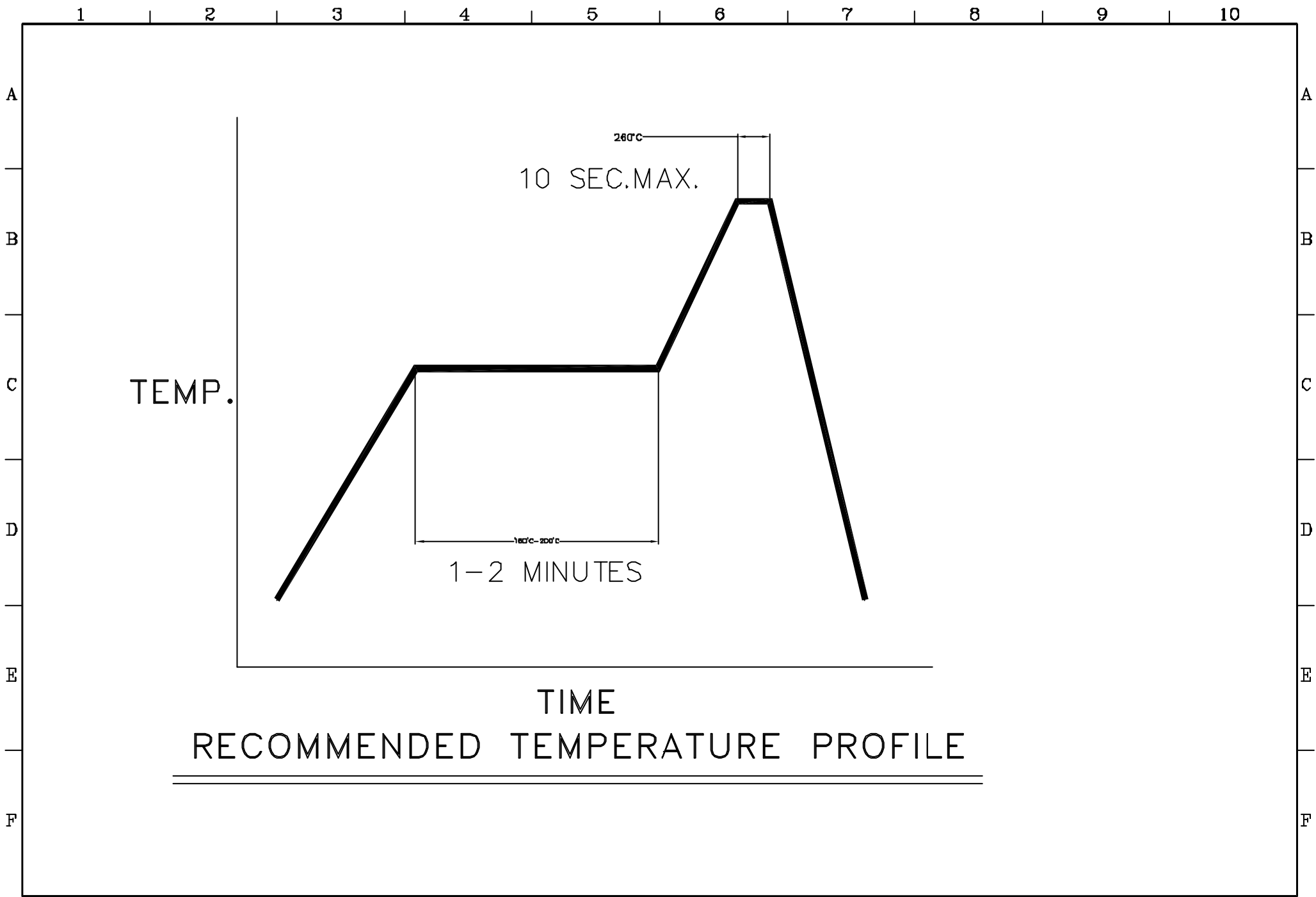
**PROPRIETARY NOTE:**  
THIS DOCUMENT C

X. ± 0.38[.015] APPD: Mari Chen 4.22'2004  
.X ± 0.25[.010] CHKD: Mari Chen 4.22'2004  
.XX ± 0.13[.005] DR: Betty Tai 4.22'2004  
.XXX±  
X' ± 3'  
.X' ±

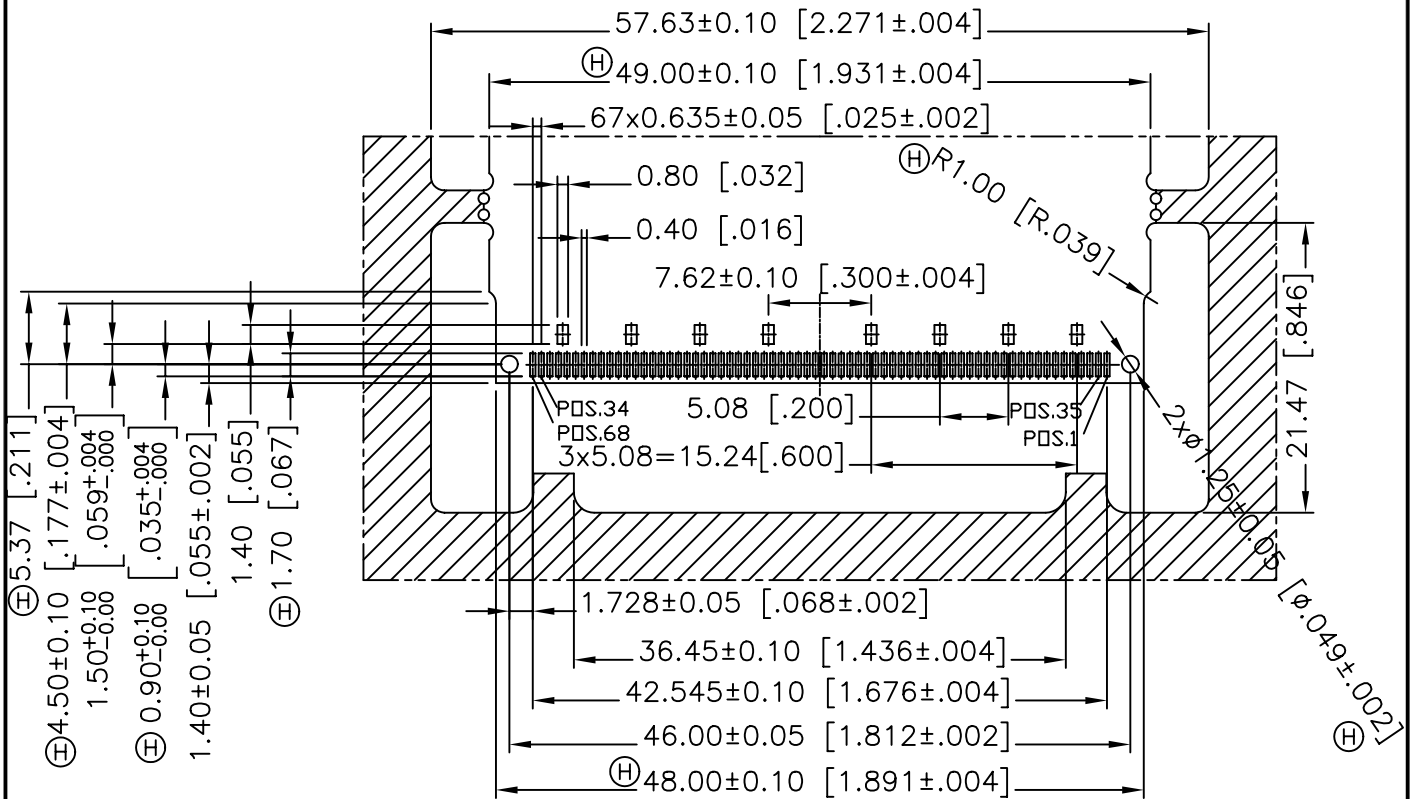
UNITS: mm [INCH] SCALE: NONE

**Mega-Chip Electronics Pte Ltd**


TITLE: CONN. PCMCIA RECV. H TYPE CARDBUS 68P, +0.30/+0.60mm OFFSET  
DWG NO: 903-007-0000  
SHEET: 2 OF 6 REV: J



RECOMMENDED TEMPERATURE PROFILE



RECOMMENDED PC BOARD DIMENSIONS (1:2)

TITLE: RECOMMENDED PCB DIM.	 Mega-Chip Electronics Pte Ltd
PROD SERIES: PCMCIA RECE. H TYPE CARDBUS 68P, +0.30/+0.60mm OFFSET	APPD: Mari Chen 4.22'2004
DWG NO: 903-007-0000	CHKD: Mari Chen 4.22'2004
	PR: Betty Tai 4.22'2004
	SHEET: 5 OF 6 REV: J

## Performance Criterion:

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- Electrical—

Current Rating: 0.5A max. per contact.

Contact Resistance: 40 m $\Omega$  max. initial, 20m $\Omega$  after conditioning.

Dielectric Withstanding Voltage: 500VAC. min. for 1 minute  
leakage current shall be 1mA max.

Insulation Resistance: 1000M $\Omega$  min. initial at 500VDC,  
100M $\Omega$  min. after conditioning at 500VDC.

- Mechanical—

Durability: 10,000 mating&unmating cycles in the office environment.  
5,000 cycles at harsh condition.

Mating force: 4 Kg (8.8lbs) max.

Unmating force: 0.68 Kg (1.5lbs) min.


Contact retention force: 0.50Kg (1.10lbs) min.

Vibration: no current interruption greater than 100ns.

- Environmental—

Operating Temperature: -20°C to +60°C, 95% RH.

Storage Temperature: -40°C to +70°C, 95% RH.

TITLE:  SPECIFICATION	 Mega-Chip Electronics Pte Ltd
PROD SERIES: PCMCIA RECE. H TYPE CARDBUS 68P, +0.30/+0.60mm OFFSET	APPD: Mari Chen 4.22'2004
DWG NO: 903-007-0000	CHKD: Mari Chen 4.22'2004
	PR: Betty Tai 4.22'2004
	SHEET: 6 OF 6   REV: J